

**Product Summary**

<b>V<sub>(BR)DSS</sub></b>	<b>R<sub>DS(on)TYP</sub></b>	<b>I<sub>D</sub></b>
60V	1.6Ω@10V	300mA
	1.8Ω@4.5V	

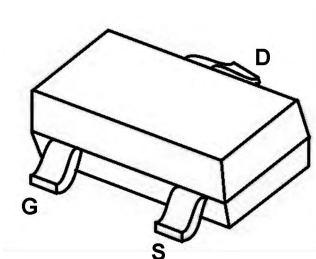
**Feature**

- High power and current handing capability
- Surface mount package
- ESD protected 2KV

**Application**

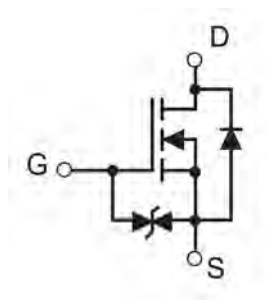
- Battery Switch
- DC/DC Converter

**Package**

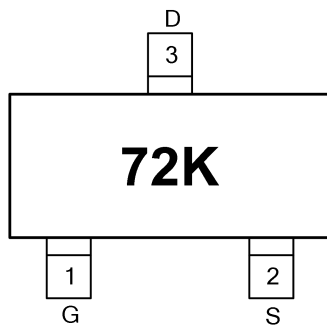


SOT-23

**Circuit diagram**



**Marking**



72K :Device Code

**Order Information**

Device	Package	Unit/Tape
2N7002BK-CN	SOT-23	3000

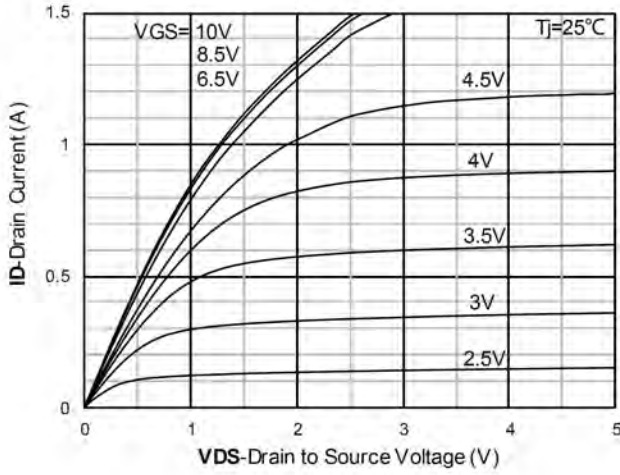
**Absolute maximum ratings (Ta=25°C, unless otherwise noted)**

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V <sub>DSS</sub>	60	V
Gate-Source Voltage	V <sub>GSS</sub>	±20	V
Continuous Drain Current (Ta=25°C)	I <sub>D</sub>	300	mA
Continuous Drain Current (Ta=100°C)	I <sub>D</sub>	200	mA
Pulse Drain Current Tested	I <sub>DM</sub>	1200	mA
Power Dissipation (Ta=25°C)	P <sub>D</sub>	350	mW
Power Dissipation (Ta=100°C)	P <sub>D</sub>	140	mW
Thermal Resistance Junction-to-Ambient	R <sub>θJA</sub>	357	°C/W
Storage Temperature Range	T <sub>STG</sub>	-55 to 150	°C
Operating Junction Temperature Range	T <sub>J</sub>	-55 to 150	°C

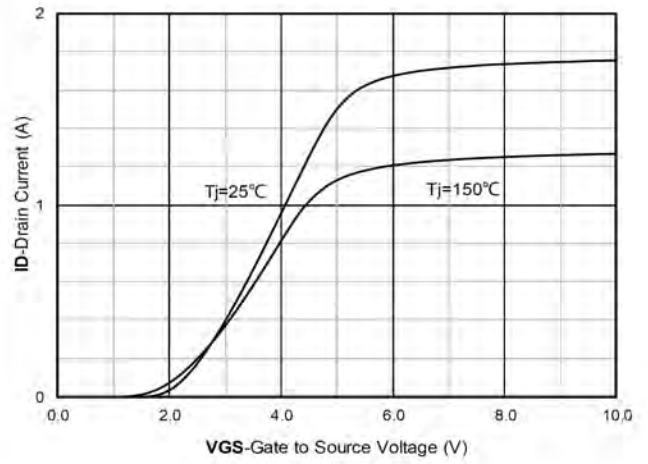
**Electrical characteristics (Ta=25°C, unless otherwise noted)**

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V , I <sub>D</sub> =250μA	60	-	-	V
Drain-Source Leakage Current	I <sub>DSS</sub>	V <sub>DS</sub> =48V , V <sub>GS</sub> =0V	-	-	1	uA
Gate-Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V , V <sub>DS</sub> =0V	-	-	±10	uA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	1	1.6	2.2	V
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V , I <sub>D</sub> =200mA	-	1.6	2	Ω
		V <sub>GS</sub> =4.5V , I <sub>D</sub> =200mA	-	1.8	2.4	
<b>Dynamic characteristics</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =30V , V <sub>GS</sub> =0V , f=1MHz	-	28	-	pF
Output Capacitance	C <sub>oss</sub>		-	10	-	
Reverse Transfer Capacitance	C <sub>rss</sub>		-	5	-	
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =30V , V <sub>GS</sub> =10V , I <sub>D</sub> =300mA	-	1.7	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	0.35	-	
Gate-Drain Charge	Q <sub>gd</sub>		-	0.5	-	
Gate Plateau Voltage	V <sub>plateau</sub>		-	3.2	-	V
<b>Switching Characteristics</b>						
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =30V , V <sub>GS</sub> =10V , R <sub>G</sub> =25Ω , I <sub>D</sub> =300mA	-	3	-	nS
Turn-On Rise Time	t <sub>r</sub>		-	17	-	
Turn-Off Delay Time	t <sub>d(off)</sub>		-	10	-	
Turn-Off Fall Time	t <sub>f</sub>		-	21	-	
<b>Source-Drain Diode characteristics</b>						
Diode Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> =0V , I <sub>S</sub> =1A , T <sub>J</sub> =25°C	-	-	1.2	V

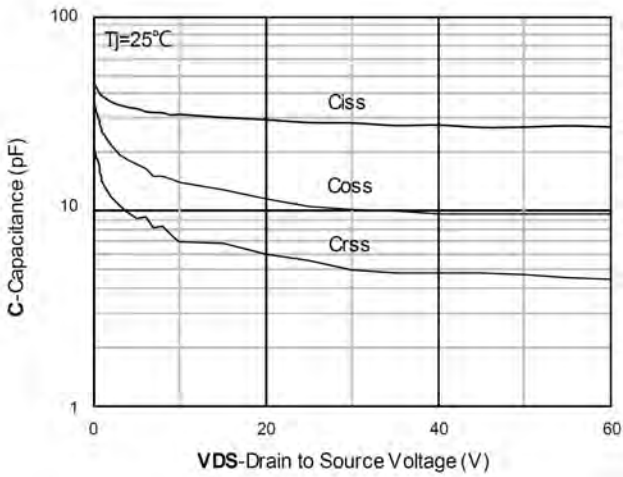
**Typical Characteristics**



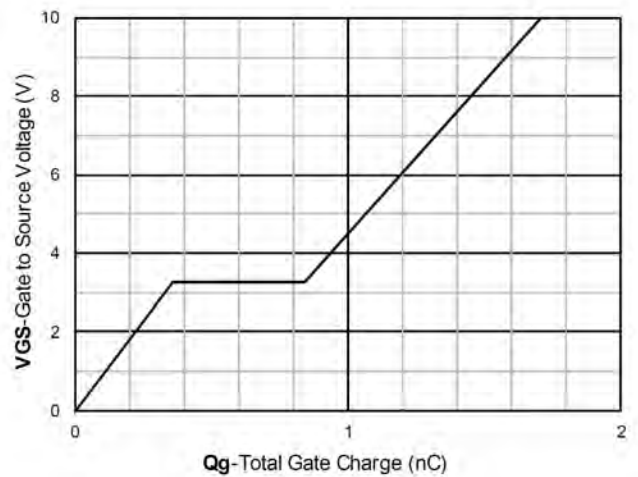
Output Characteristics



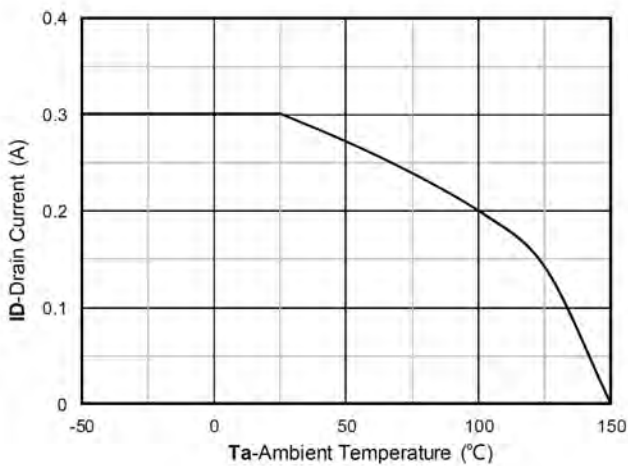
Transfer Characteristics



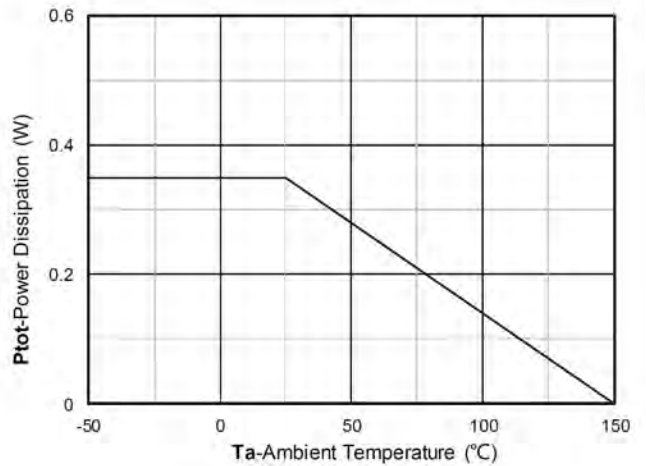
Capacitance Characteristics



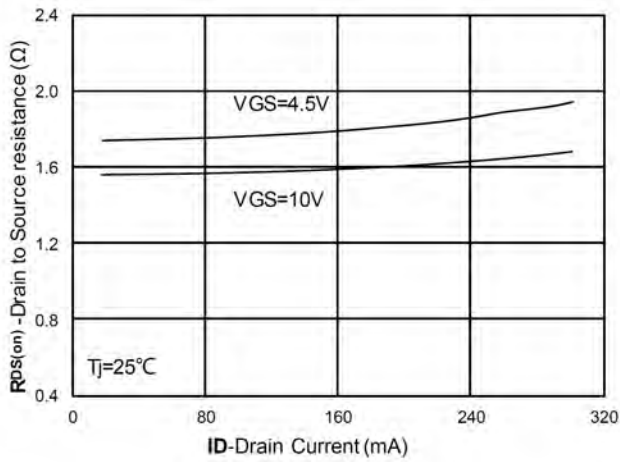
Gate Charge



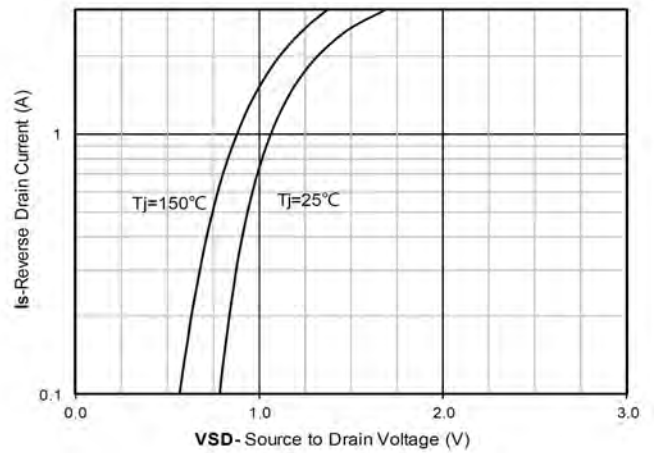
Current dissipation



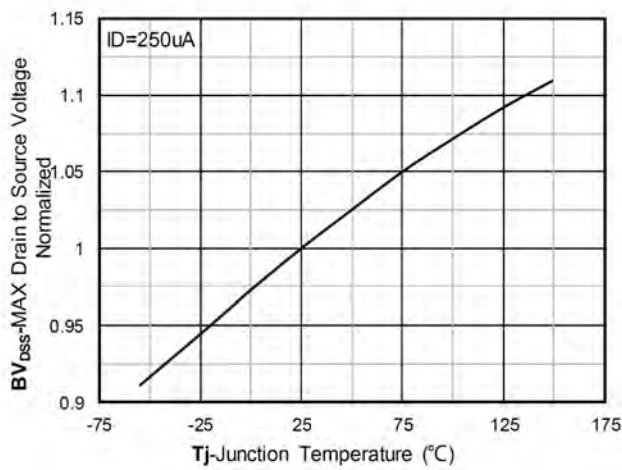
Power dissipation



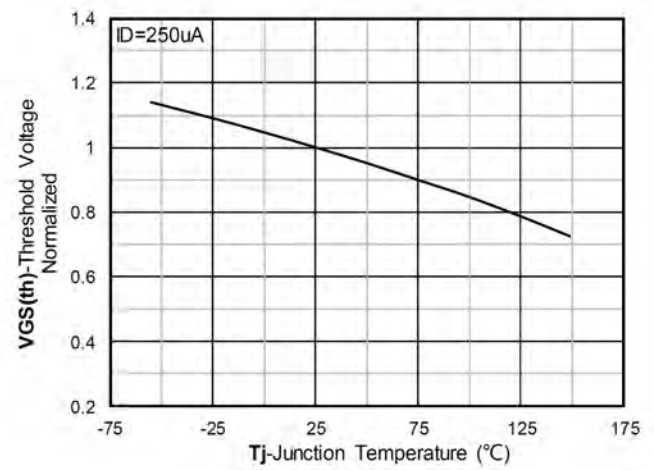
RDS(on) VS Drain Current



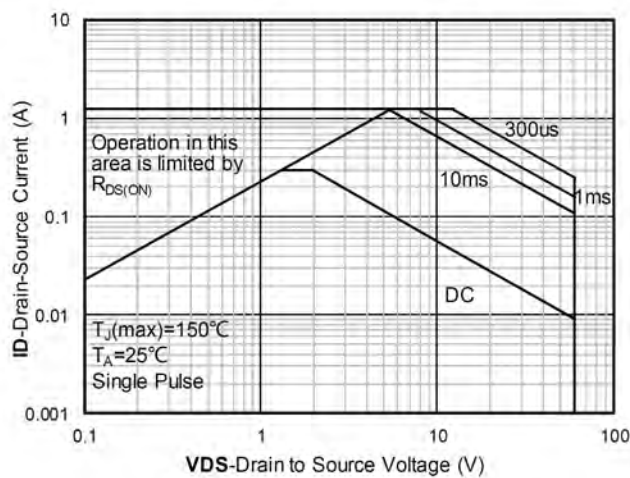
Forward characteristics of reverse diode



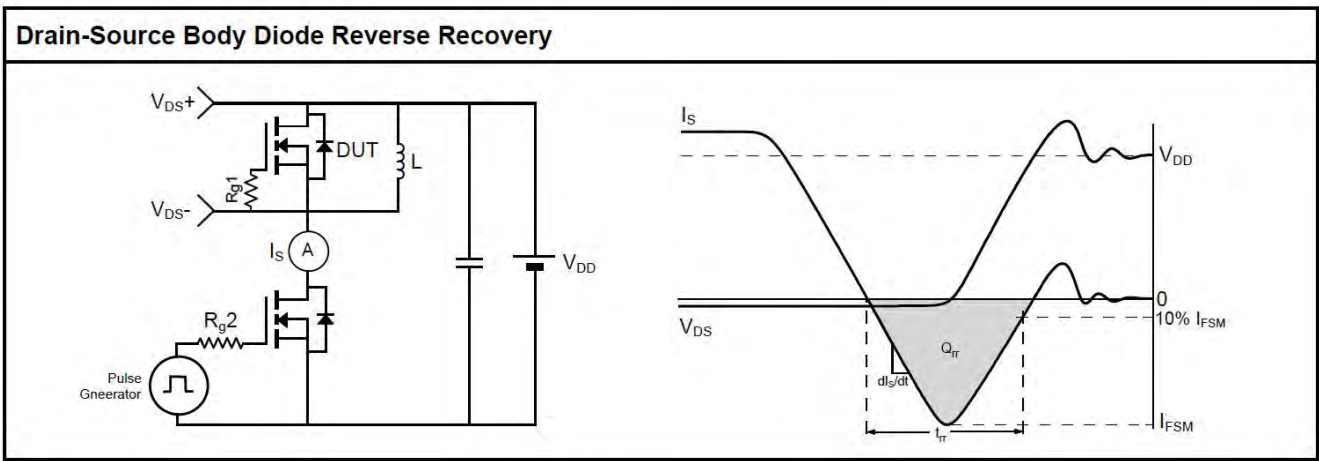
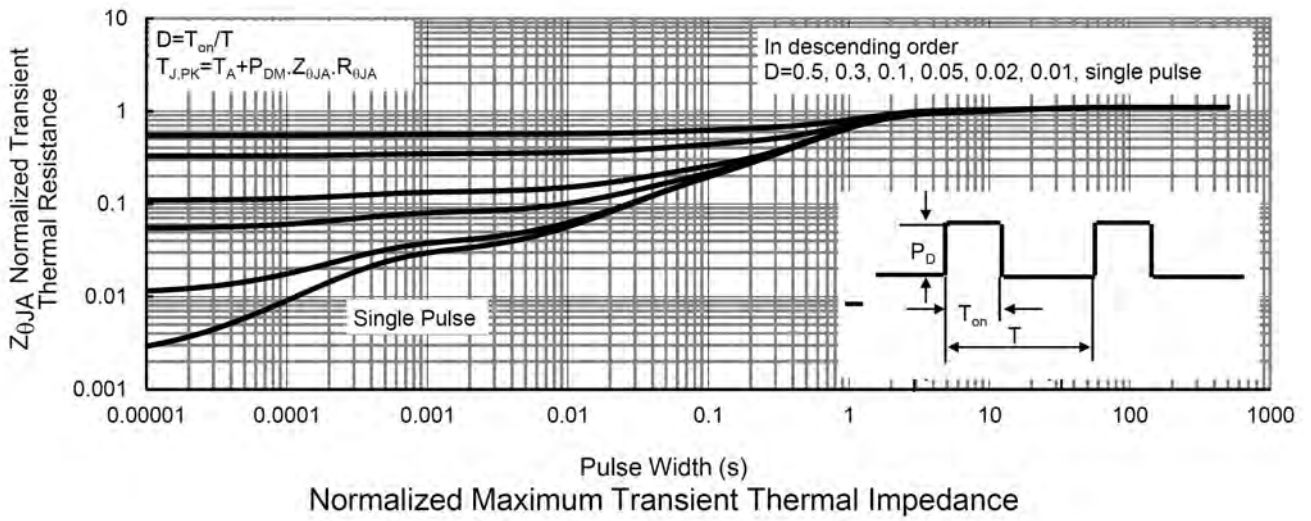
Normalized breakdown voltage



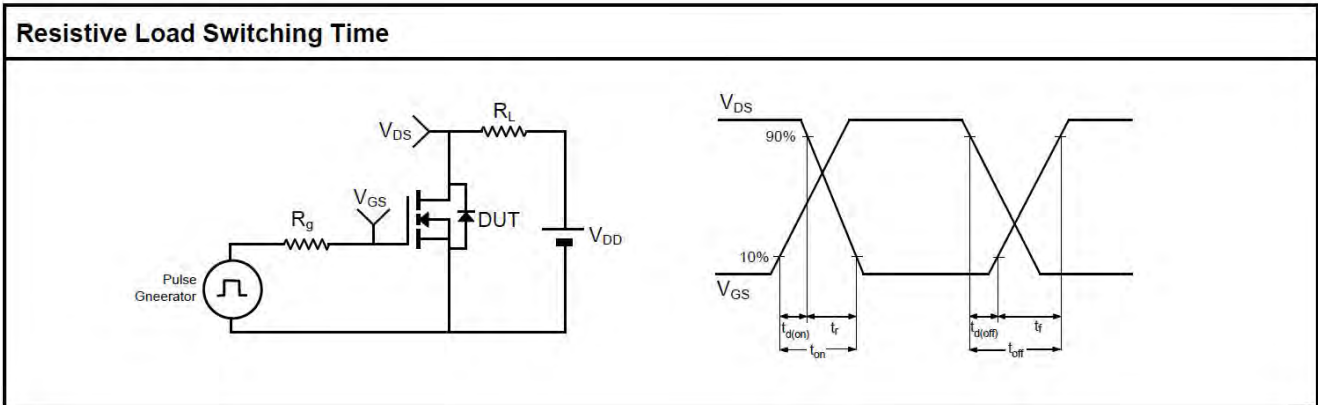
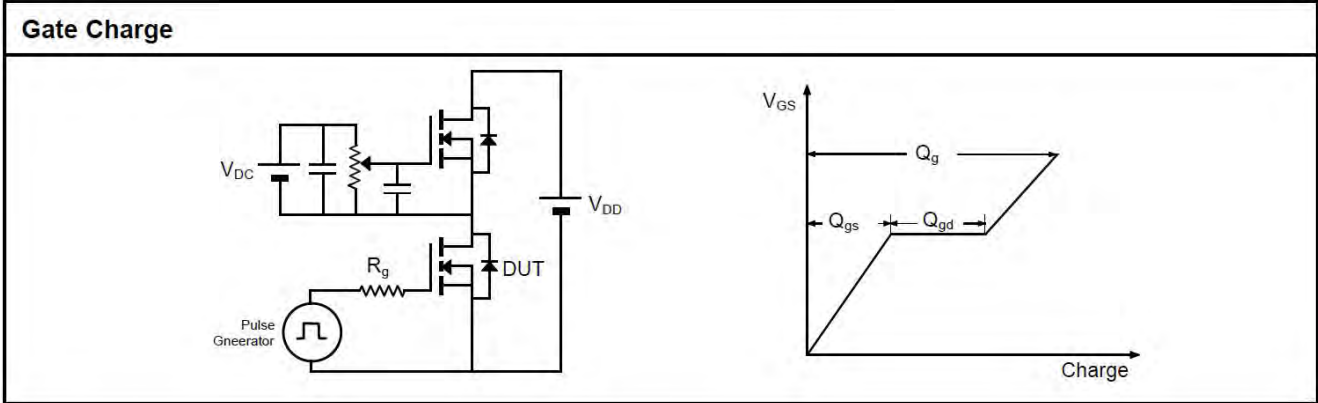
Normalized Threshold voltage



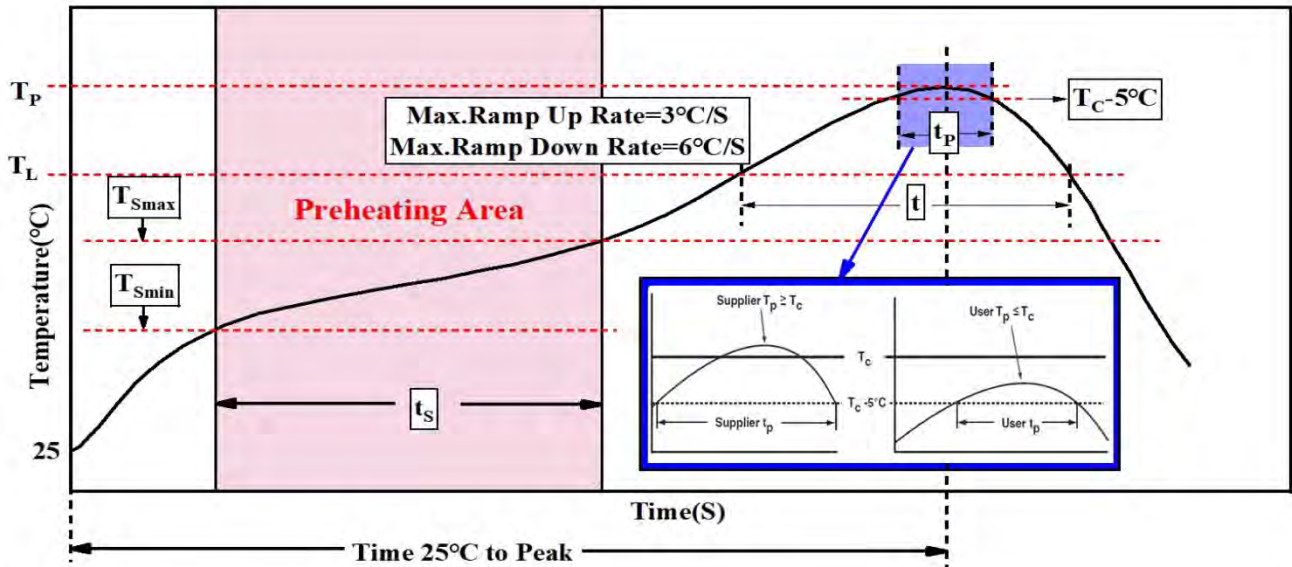
Safe Operation Area



**Test Circuit**



Temperature Profile for IR Reflow Soldering



Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
<b>Preheat &amp; Soak</b>		
Temperature min (T <sub>Smin</sub> )	100°C	150°C
Temperature max (T <sub>Smax</sub> )	150°C	200°C
Time (T <sub>Smin</sub> to T <sub>Smax</sub> ) (t <sub>s</sub> )	60-120 seconds	60-120 seconds
Average ramp-up rate (T <sub>Smax</sub> to T <sub>p</sub> )	3 °C/second max.	3°C/second max.
Liquidous temperature (T <sub>L</sub> )	183 °C	217°C
Time at liquidous (t <sub>L</sub> )	60-150 seconds	60-150 seconds
Peak package body Temperature e (T <sub>p</sub> )*	See Classification Temp in table 1	See Classification Temp in table 2
Time (t <sub>p</sub> )** within 5°C of the specified classification temperature (T <sub>c</sub> )	20** seconds	30** seconds
Average ramp-down rate (T <sub>p</sub> to T <sub>Smax</sub> )	6 °C/second max.	6 °C/second max.
Time 25°C to peak temperature	6 minutes max.	8 minutes max.
* Tolerance for peak profile Temperature (T <sub>p</sub> ) is defined as a supplier minimum and a user maximum. ** Tolerance for time at peak profile temperature (t <sub>p</sub> ) is defined as a supplier minimum and a user maximum		

Table 1. SnPb Eutectic Process – Classification Temperatures (T<sub>c</sub>)

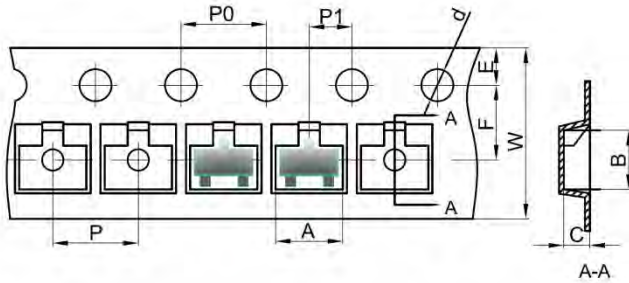
Package Thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> ≥350
<2.5 mm	235 °C	220 °C
≥2.5 mm	220 °C	220 °C

Table 2. Pb-free Process – Classification Temperatures (T<sub>c</sub>)

Package Thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> 350-2000	Volume mm <sup>3</sup> >2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 mm – 2.5 mm	260 °C	250 °C	245 °C
≥2.5 mm	250 °C	245 °C	245 °C

SOT-23 Tape and Reel

SOT-23 Embossed Carrier Tape

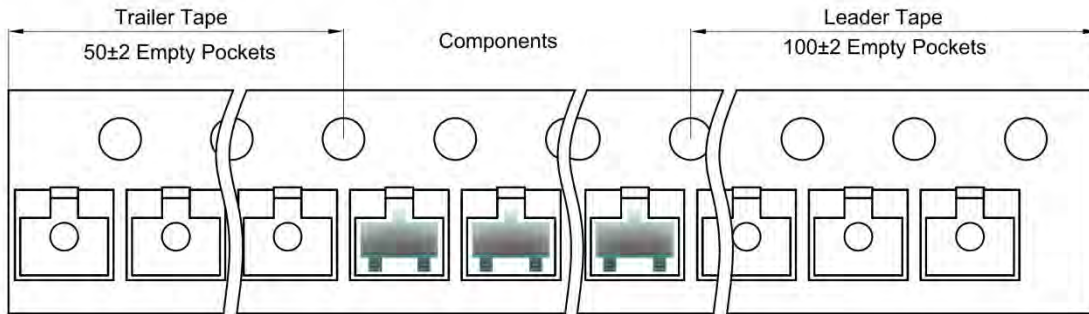


**Packaging Description:**  
 SOT-23 parts are shipped in tape. The carrier tape is made from a dissipative (carbon filled) polycarbonate resin. The cover tape is a multilayer film (Heat Activated Adhesive in nature) primarily composed of polyester film, adhesive layer, sealant, and anti-static sprayed agent. These reeled parts in standard option are shipped with 3,000 units per 7" or 17.8cm diameter reel. The reels are clear in color and is made of polystyrene plastic (anti-static coated).

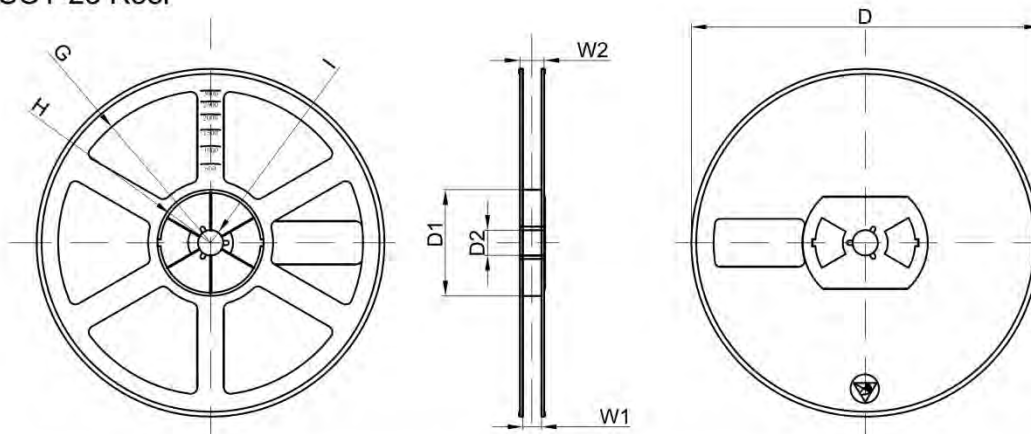
Dimensions are in millimeter

Pkg type	A	B	C	d	E	F	P0	P	P1	W
SOT-23	3.15	2.77	1.22	Ø1.50	1.75	3.50	4.00	4.00	2.00	8.00

SOT-23 Tape Leader and Trailer



SOT-23 Reel

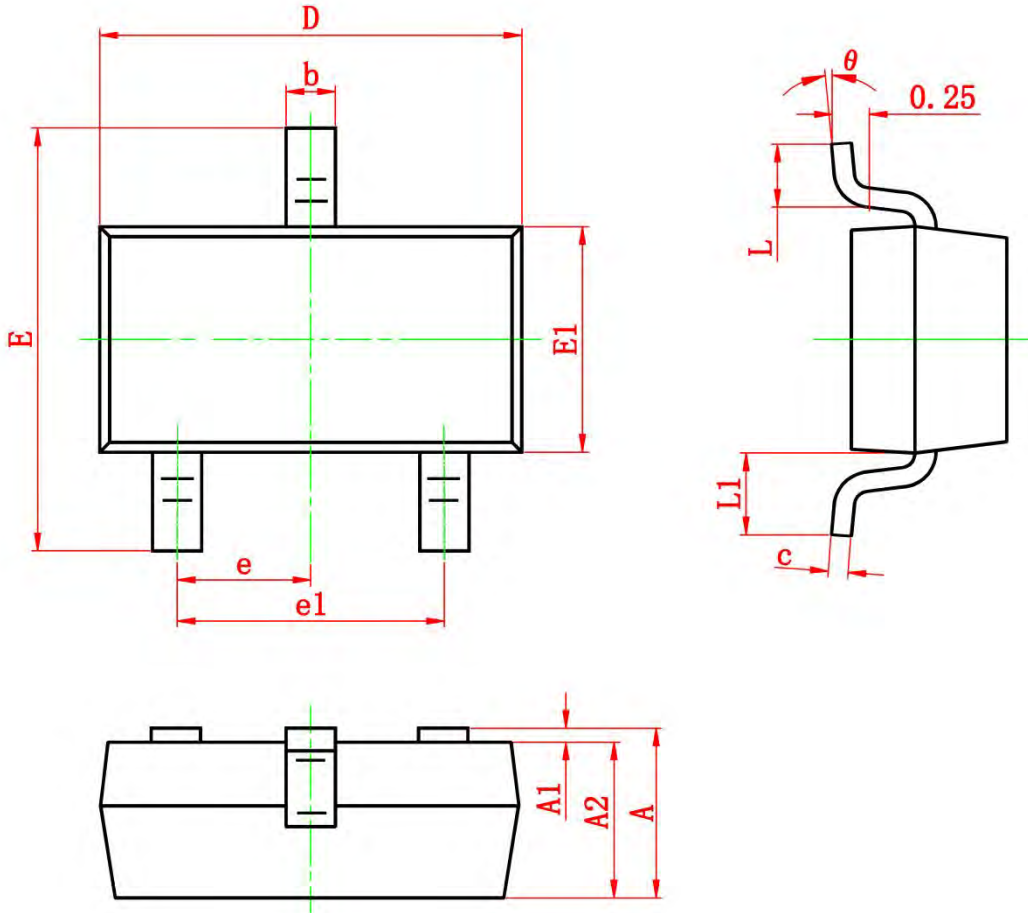


Dimensions are in millimeter

Reel Option	D	D1	D2	G	H	I	W1	W2
7" Dia	Ø178.00	54.40	13.00	R78.00	R25.60	R6.50	9.50	12.30

REEL	Reel Size	Box	Box Size(mm)	Carton	Carton Size(mm)	G.W.(kg)
3000 pcs	7 inch	45,000 pcs	203×203×195	180,000 pcs	438×438×220	

SOT-23 Package Information



Symbol	Dimensions In Millimeters	
	Min.	Max.
A	0.90	1.15
A1	0.00	0.125
A2	0.90	1.050
b	0.30	0.50
c	0.08	0.15
D	2.80	3.00
E1	1.20	1.40
E	2.25	2.55
e	0.95 REF.	
e1	1.80	2.00
L	0.55 REF.	
L1	0.30	0.50
$\theta$	0°	8°

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